

AMENDMENTS TO THE SPECIFICATION

Please replace the first full paragraph on page 14 of the specification with the following amended paragraph:

Examples of the radiator include a heat sink and a thermal via. Examples of the connection terminal include a pin terminal, a lead terminal, a flip chip terminal, a land terminal and a solder ball terminal. Examples of the cover include a plate-like metal-made lid and a ceramic-made lid. Examples of the circuit component include electronic components such as semiconductor element, condenser, inductor and ~~register~~ resistor.

Please replace the first full paragraph on page 16 of the specification with the following amended paragraph:

~~{Fig. 1}~~ The Drawing

~~Fig. 1~~ The drawing is a cross-sectional view showing the structure of a wiring board according to the embodiment of the present invention.

Please replace the second full paragraph on page 23 of the specification with the following amended paragraph:

~~Fig. 1~~ The drawing is a cross-sectional view showing the structure of a wiring board according to the embodiment of the present invention.

Please replace the third full paragraph on page 23 of the specification with the following amended paragraph:

In ~~Fig. 1~~ the drawing, 1 is a wiring board and the wiring board 1 comprises a ceramic substrate 2 formed by stacking a plurality of ceramic green sheets and firing them, a radiator 3 joined to the bottom face of the ceramic substrate 2 through a brazing material 12, a

semiconductor element 4 inserted in the hole of the ceramic substrate 2 and disposed on the top face of the radiator 3, a cover 7 shielding the hole of the ceramic substrate 2 to cover the semiconductor 4 and connected to the conductor layer 10 through a brazing material 13, and a connection terminal 6 connected to the conductor layer 10 on the top face of the ceramic substrate 2 through a brazing material 14.